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Mira et al.

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(54) **POWER HEAT SINK WITH HYBRID VAPOR CHAMBER—HEAT PIPE MODULE**

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(73) Assignee: **Heatscape, Inc.**, Morgan Hill, CA (US)

(*) Notice: This patent is subject to a terminal disclaimer.

(**) Term: **14 Years**

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(51) **LOC (10) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/179**

(58) **Field of Classification Search**
CPC . H01L 23/427; H01L 23/467; H01L 23/3672; H01L 23/3677; H05K 7/20154; F28D 15/0233; F28D 15/0266; F28D 15/0275
USPC D13/179; 165/80.3, 104.26, 104.33, 165/122, 151, 185; 257/706, 707, 718–722; 361/695, 697, 700, 702, 704, 709, 710, 361/711, 719
See application file for complete search history.

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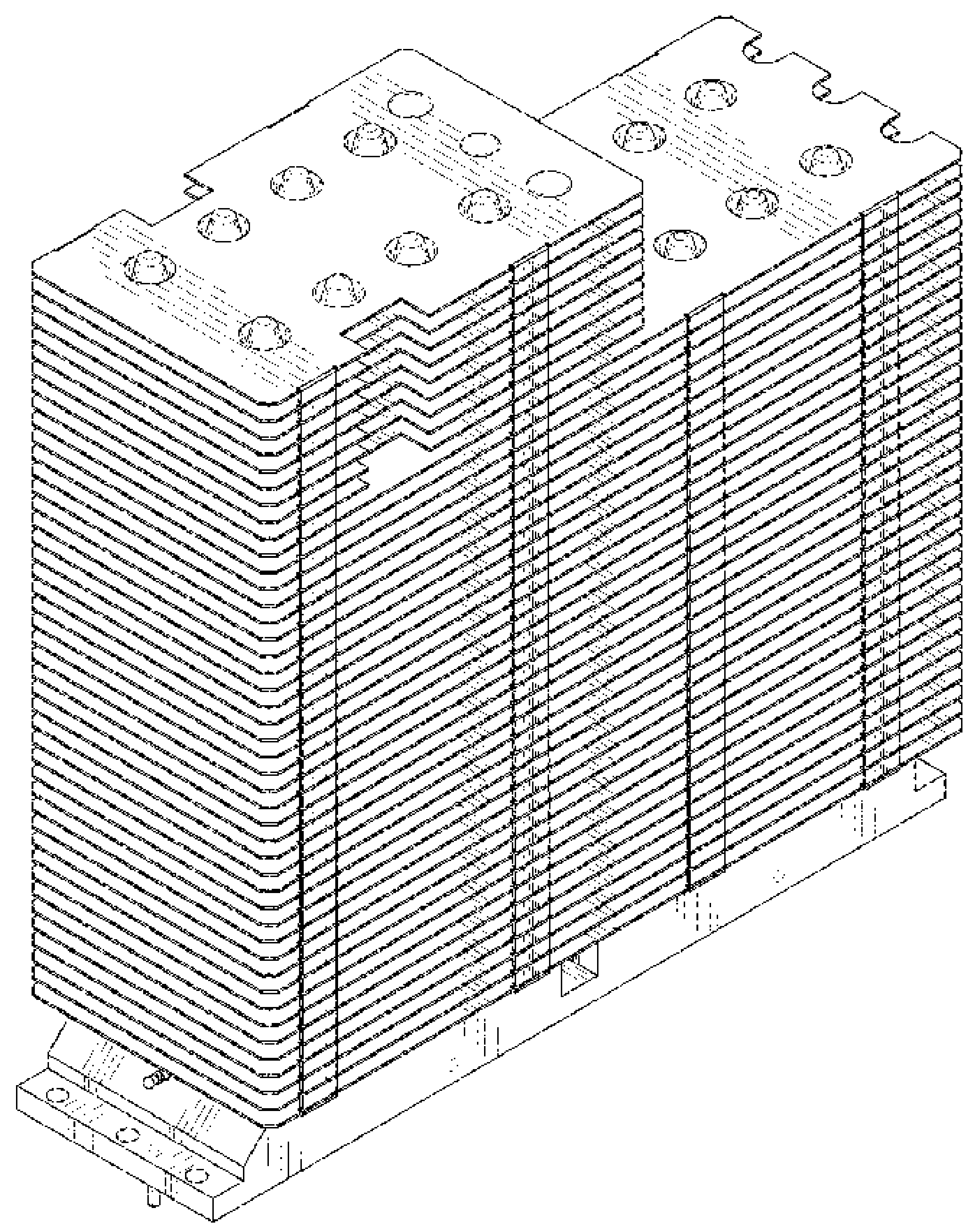
(57) **CLAIM**

The ornamental design for a power heat sink with hybrid vapor chamber—heat pipe module, as shown and described.

DESCRIPTION

FIG. **1** is a top perspective view of a power heat sink with hybrid vapor chamber—heat pipe module showing our new design;
FIG. **2** is a front elevational view thereof;
FIG. **3** is a top plan view thereof;
FIG. **4** is a bottom plan view thereof;
FIG. **5** is a left side elevational view thereof;
FIG. **6** is a right side elevational view thereof;
FIG. **7** is an additional perspective view thereof; and,
FIG. **8** is a disassembled view corresponding to FIG. **7**.
The broken line showing on the drawing disclosure is for illustrative purposes only and forms no part of the claimed design.

1 Claim, 6 Drawing Sheets



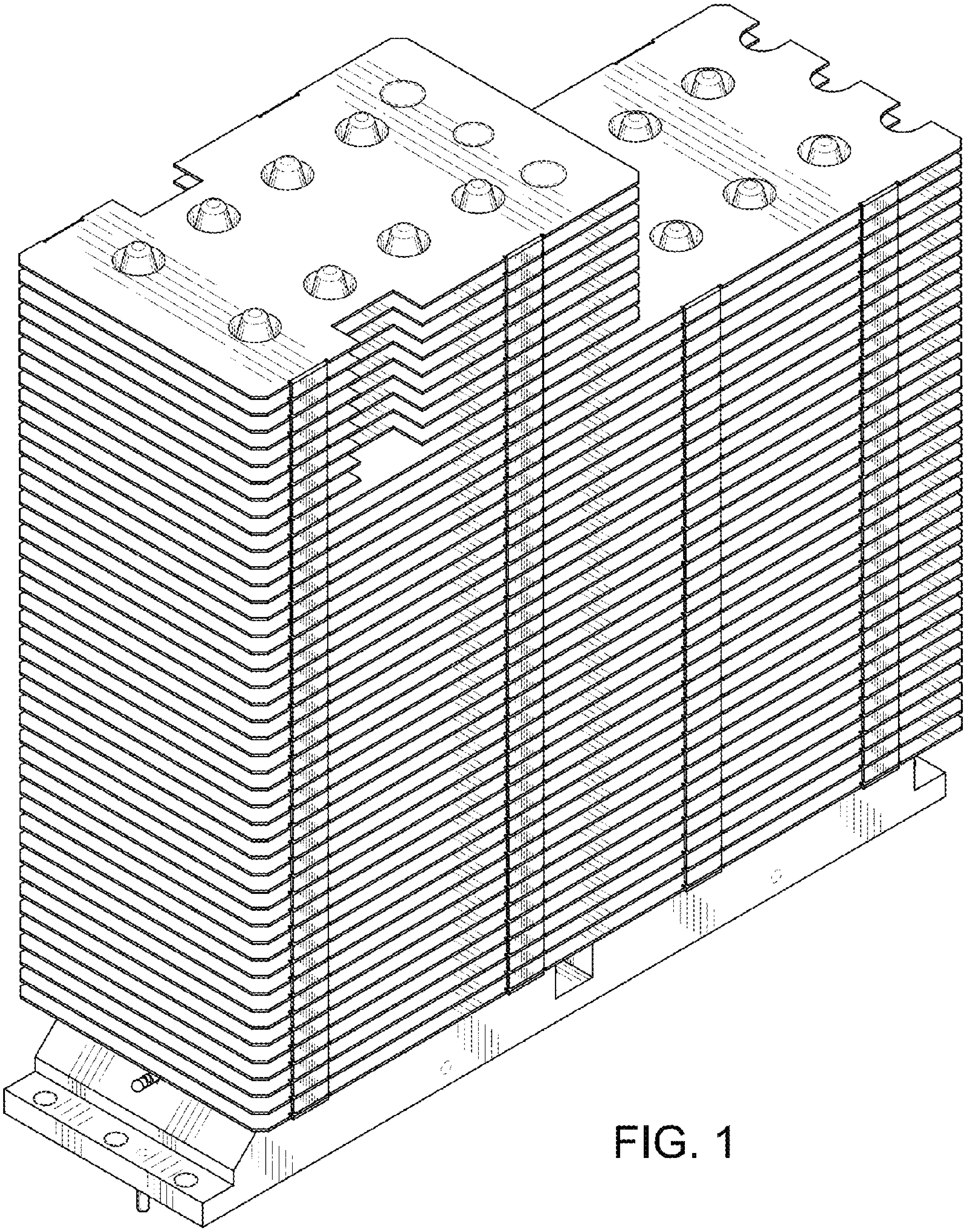


FIG. 1

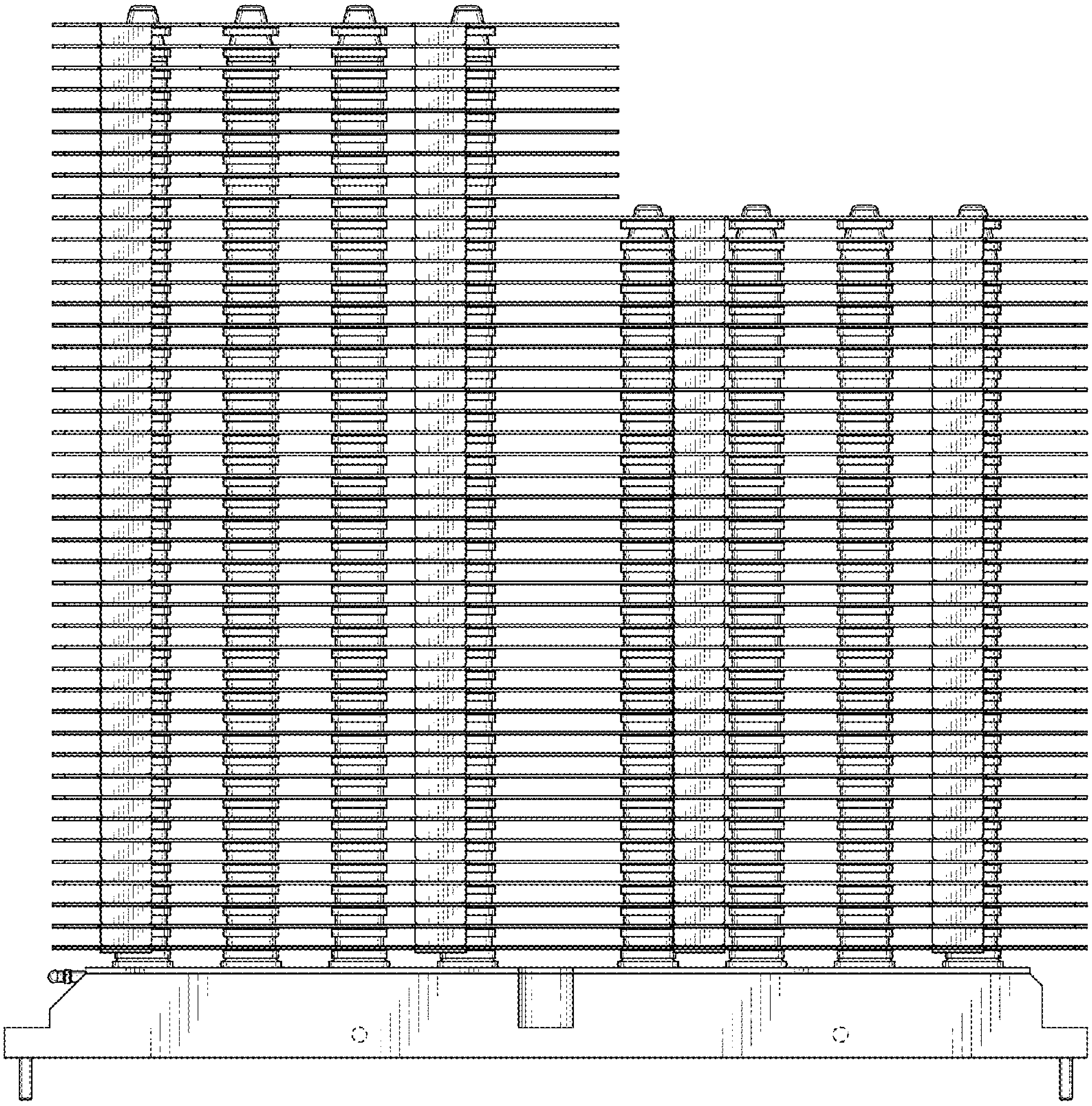


FIG. 2

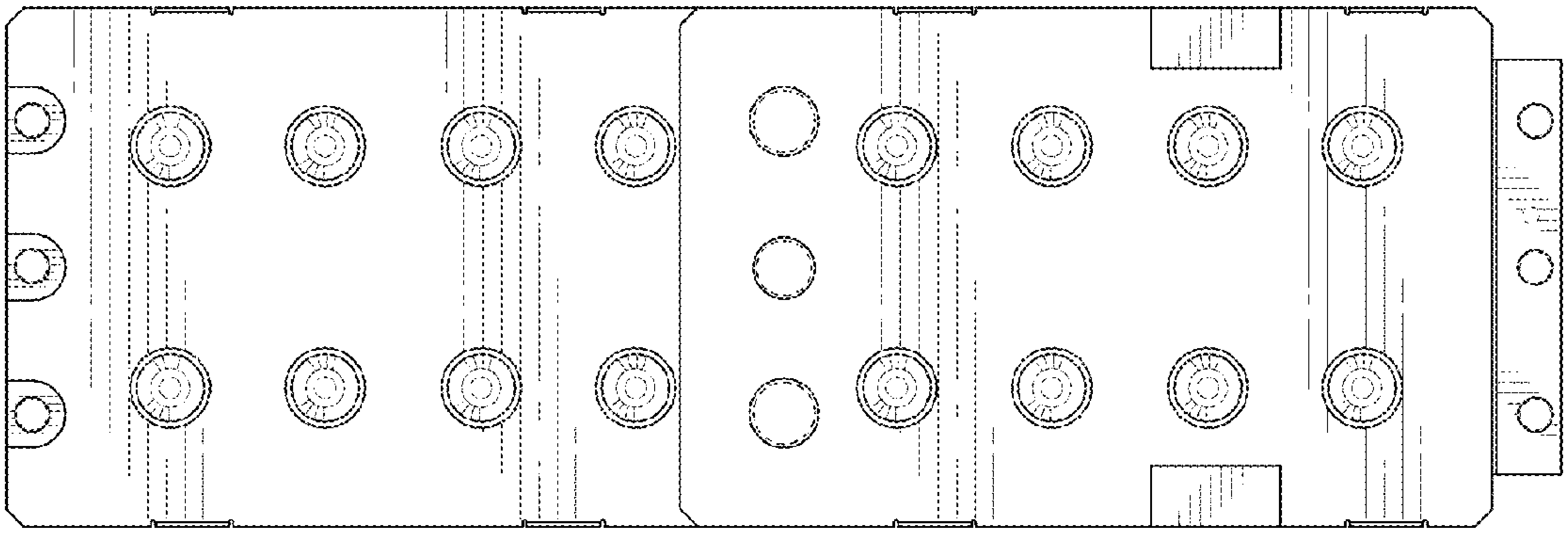


FIG. 3

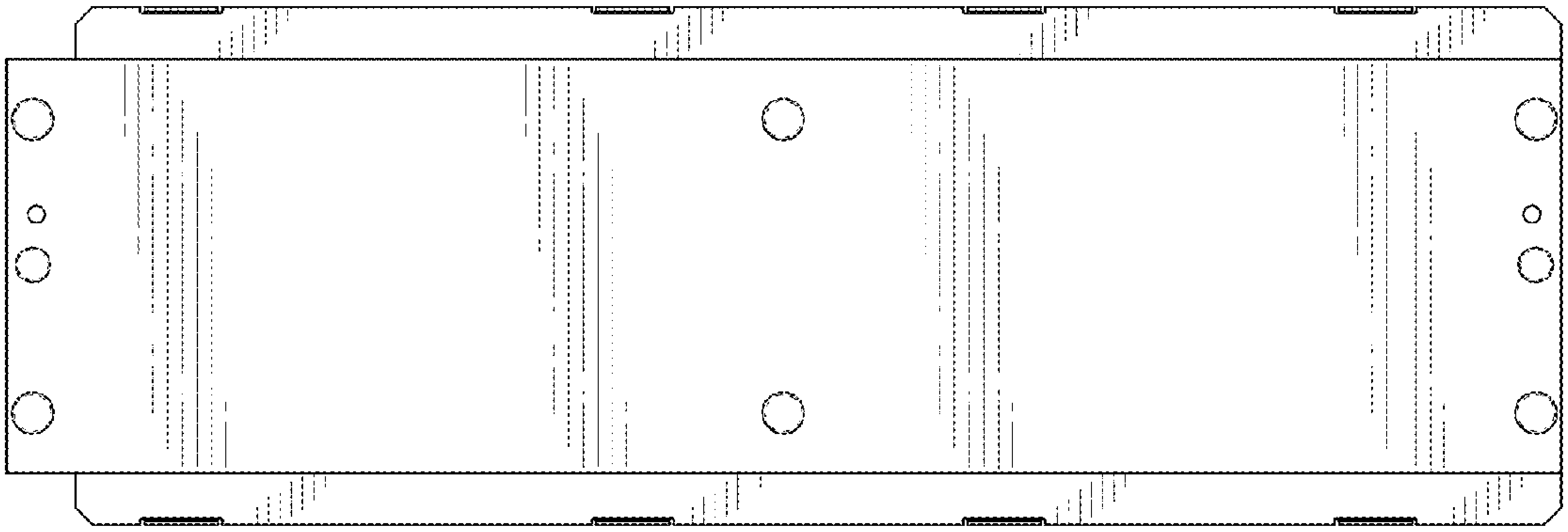


FIG. 4

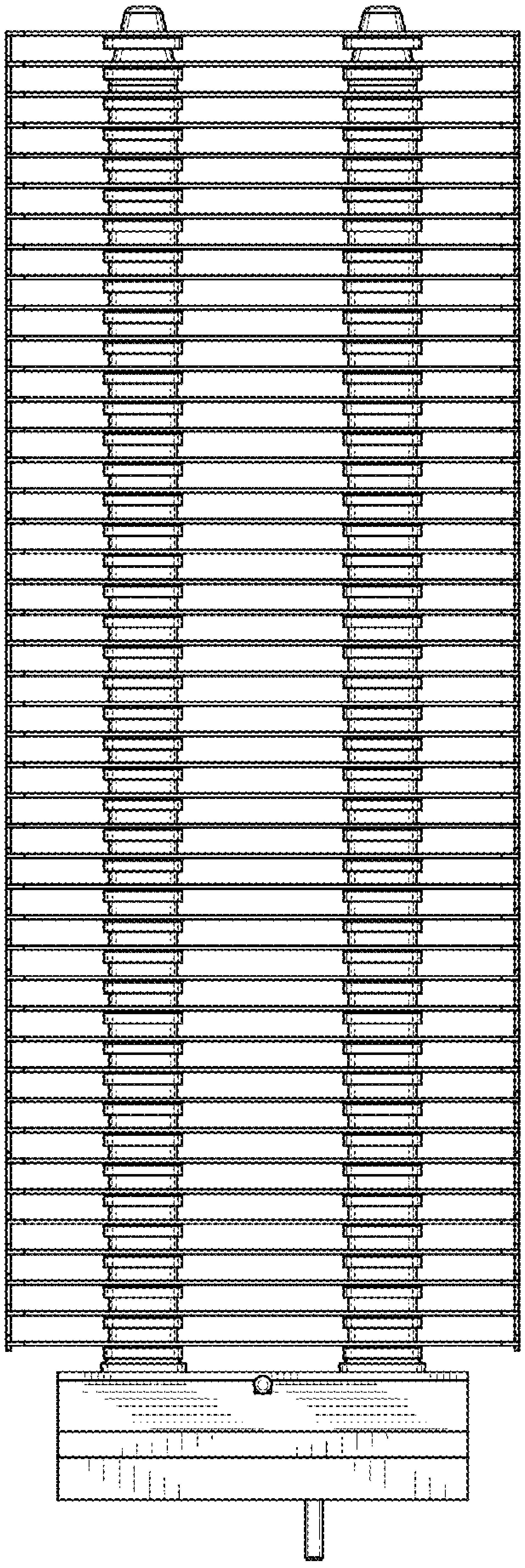


FIG. 5

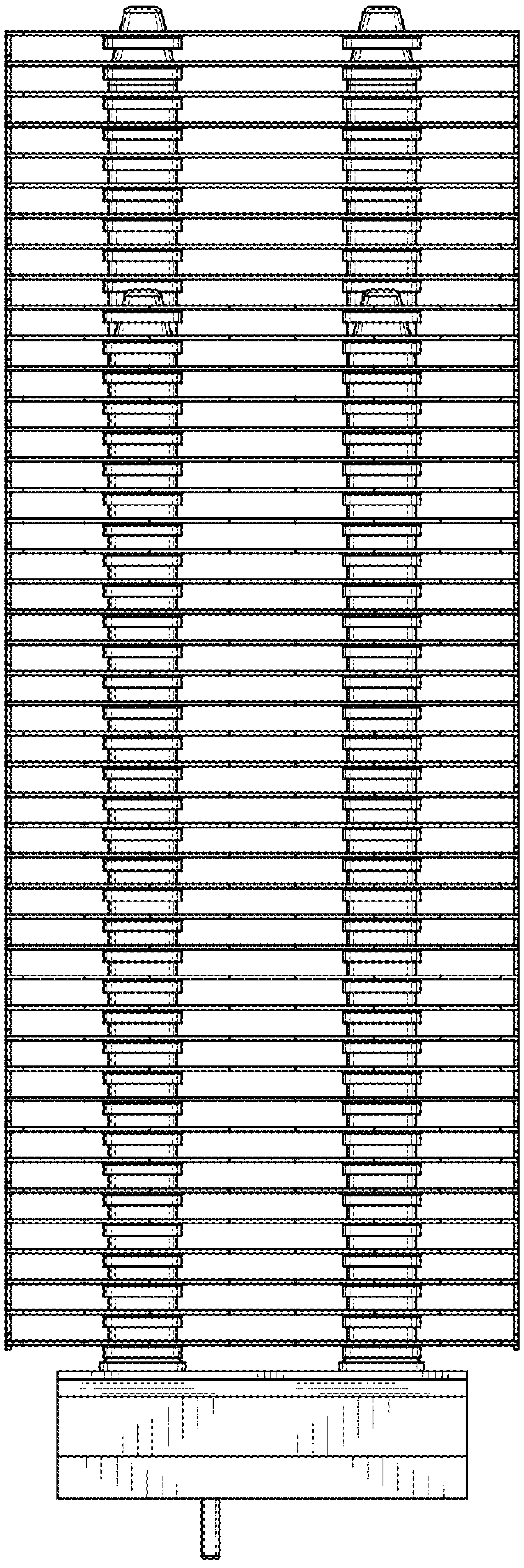


FIG. 6

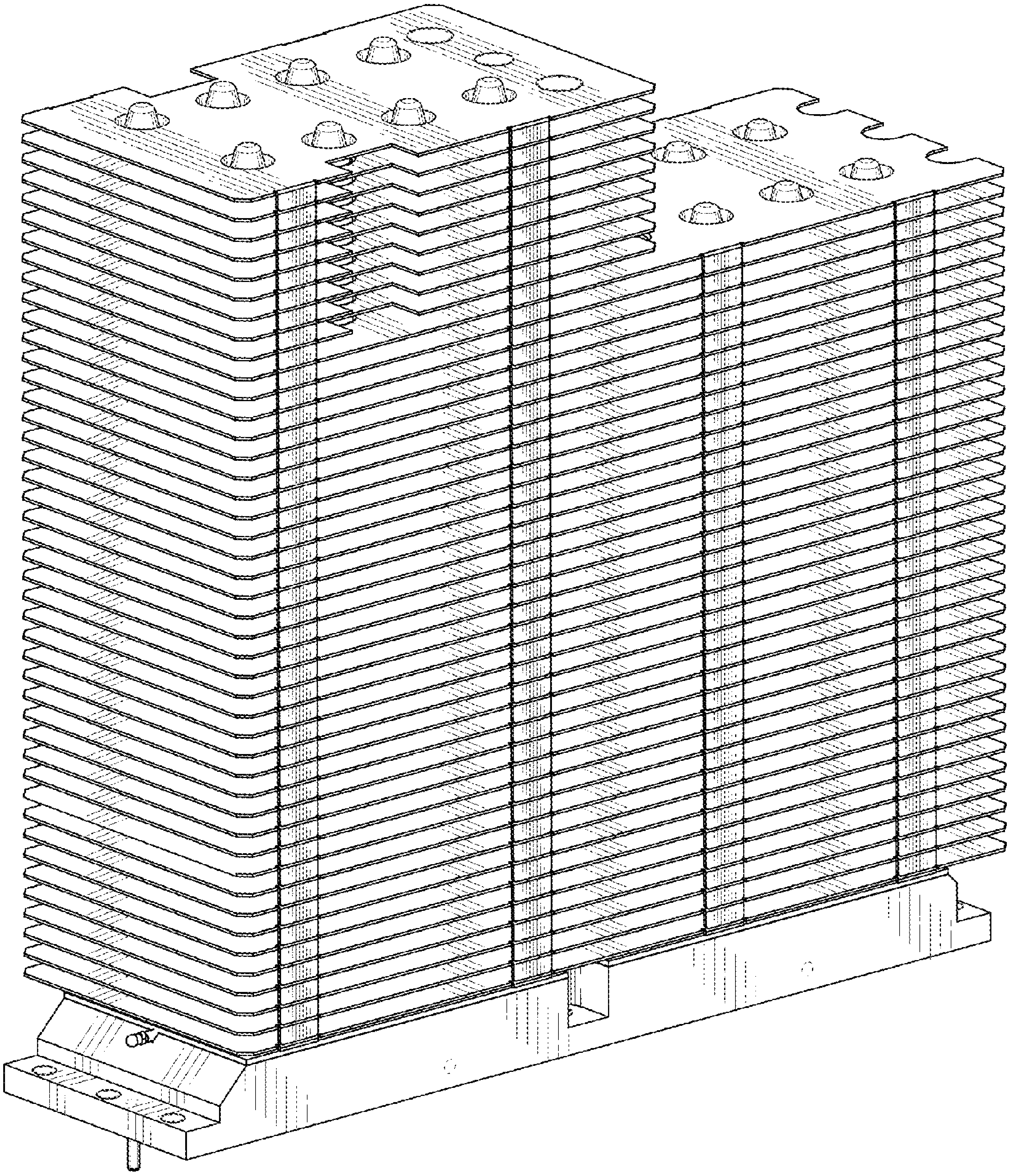


FIG. 7

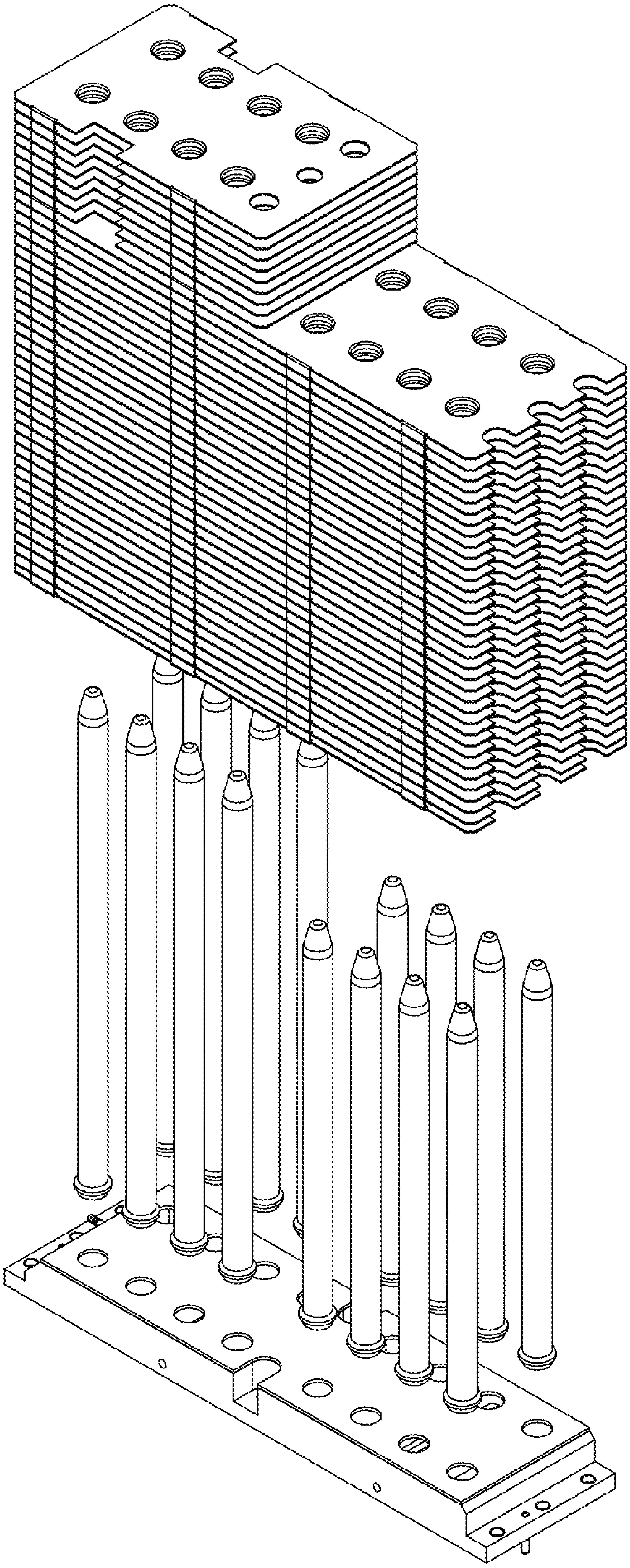


FIG. 8